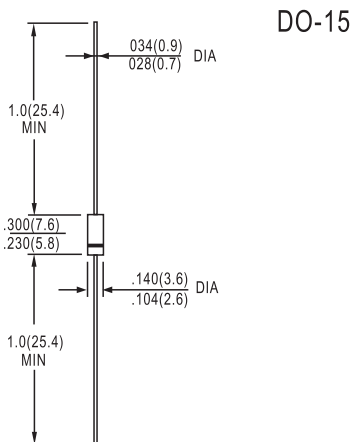


FEATURES

- High temperature metallurgically bonded construction
- Sintered glass cavity free junction
- Capability of meeting environmental standard of MIL-S-19500
- High temperature soldering guaranteed
- 350°C /10sec/0.375"lead length at 5 lbs tension
- Operate at Ta =55°C with no thermal run away
- Typical Ir<0.1μA

MECHANICAL DATA

Terminal: Plated axial leads solderable per
MIL-STD 202E, method 208C
Case: Molded with UL-94 Class V-0 recognized Flame
Retardant Epoxy
Polarity: color band denotes cathode
Mounting position: any



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(single-phase, half-wave, 60HZ, resistive or inductive load rating at 25°C, unless otherwise stated)

	SYMBOL	BYV26EGP-15	units
Maximum Recurrent Peak Reverse Voltage	V _{rrm}	1000	V
Maximum RMS Voltage	V _{rms}	700	V
Maximum DC blocking Voltage	V _{dc}	1000	V
Reverse avalanche breakdown voltage at I _R = 0.1 mA	V _{(BR)R}	1100min	V
Maximum Average Forward Rectified Current 3/8"lead length at Ta =55°C	I _{f(av)}	1.0	A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	I _{fsm}	30	A
Maximum Forward Voltage at rated Forward Current and 50°C	V _f	2.5	V
Non-repetitive peak reverse avalanche energy (Note 1)	E _{rs}	10	mJ
Maximum DC Reverse Current Ta =25°C at rated DC blocking voltage Ta =150°C	I _r	5.0 150.0	μA
Maximum Reverse Recovery Time (Note 2)	T _{rr}	75	nS
Typical Junction Capacitance (Note 3)	C _j	15.0	pF
Typical Thermal Resistance (Note 4)	R _{th(ja)}	55.0	°C /W
Storage and Operating Junction Temperature	T _{stg} , T _j	-65 to +175	°C

Note: 1.R=400mA; T_j=T_{jmax} prior to surge; inductive load switched off
2.Reverse Recovery Condition I_f =0.5A, I_r =1.0A, I_{rr} =0.25A
3.Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc
4.Thermal Resistance from Junction to Ambient at 3/

RATINGS AND CHARACTERISTICS CURVES

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FIG. 1 - FORWARD CURRENT DERATING CURVE

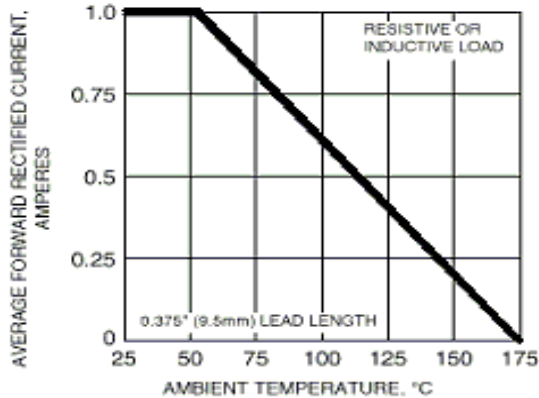


FIG. 2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

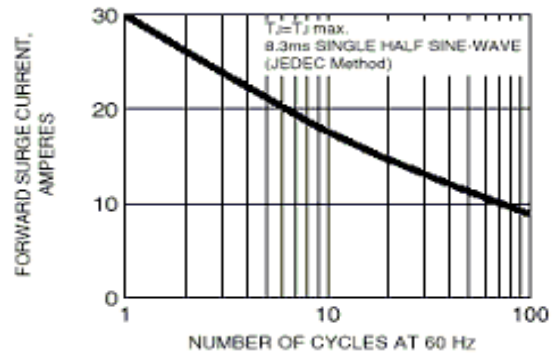


FIG. 3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

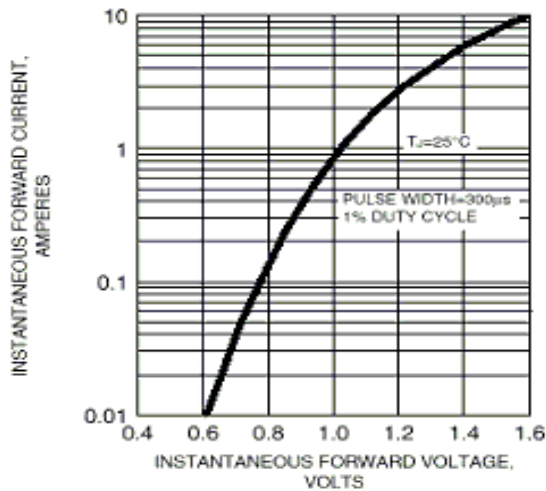


FIG. 4 - TYPICAL REVERSE CHARACTERISTICS

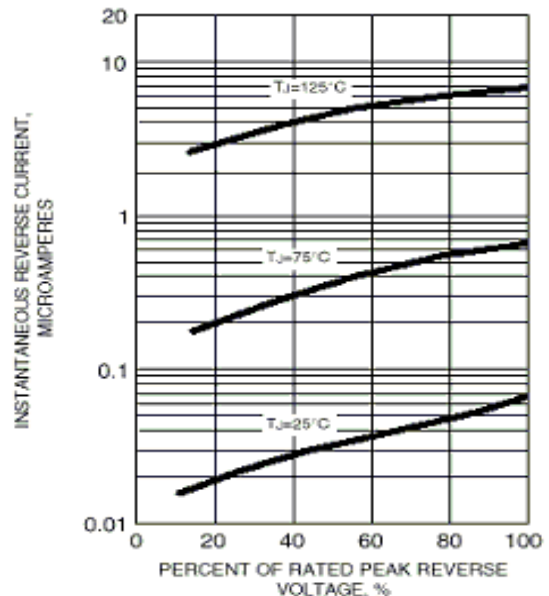


FIG. 5 - TYPICAL JUNCTION CAPACITANCE

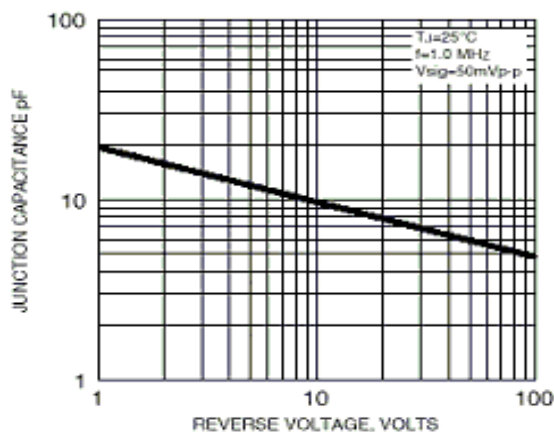


FIG. 6 - TYPICAL TRANSIENT THERMAL IMPEDANCE

